


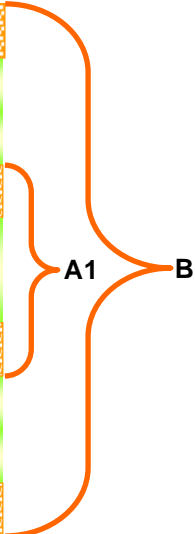




Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
---	---	---	---	---	---	-----------

04 105 FR4 95 L41.105 P06

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

04_105_FR4_95_L41.105_p06

Layers	in μ	Material	Build-Up	Assembly
Layer-1	95 μ	Copper		
	60 μ	Prepreg		
	60 μ	Prepreg		
Layer-2	105 μ	Copper		
	410 μ	L-FR4		
Layer-3	105 μ	Copper		
	60 μ	Prepreg		
	60 μ	Prepreg		
Layer-99	95 μ	Copper		

© Copyright by Printed Circuit Boards GmbH